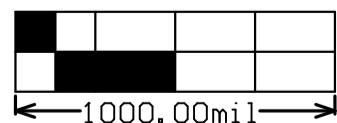


10000.00mil

6690.00mil



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.50mil	3.5	
3	Layer 1 - Top Layer	Copper	1.70mil		
4	Dielectric1	370HR	4.05mil	4.2	
5	Layer 2 - GND	Copper	1.18mil		
6	Dielectric2	370HR	27.95mil	4.2	
7	Layer 3 - PWR	Copper	1.18mil		
8	Dielectric3	370HR	8.11mil	4.2	
9	Layer 4 - Signal	Copper	1.18mil		
10	Dielectric4	370HR	27.95mil	4.2	
11	Layer 5 - GND	Copper	1.18mil		
12	Dielectric5	370HR	4.05mil	4.2	
13	Layer 6 - Bottom Layer	Copper	1.70mil		
14	Bottom Solder	Solder Resist	0.50mil	3.5	
15	Bottom Overlay				

MIN. TRACK WIDTH: 0.1 mm
 MIN. CLEARANCE: 0.13mm
 MIN. VIA PAD SIZE: 0.5 mm
 MINIMUM ANNULAR RING 0.05mm (2ML) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
 HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
 FR-408 FR-4 High Tg OTHER _____
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER 82 MIL
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FILES
 PTH COPPER THICKNESS: 20-30 um OTHER _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR: GREEN OTHER _____
 MATTE SEMI-GLOSS

SURFACE FINISH: IMMERSION GOLD (ENIG) ENIG
 IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER M1 BOARD OUTLINE
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 RoHS OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
 PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER



PROJECT TITLE:
 ADAS Sensor Fusion Board

DESIGNED FOR:
 Public Release

FILE NAME:
 PCB1_test.PcbDoc

ENGINEER:
 Spectrum Digital

LAYOUT BY:
 Spectrum Digital

SCALE: 1.00

ALTIUM DESIGNER VERSION:
 17.0.11.656

Symbol	Count	Hole Size	Plated
▽	503	7.87mil (0.200mm)	PTH
✕	822	10.00mil (0.254mm)	PTH
⊕	73	15.00mil (0.381mm)	PTH
◇	6	24.00mil (0.610mm)	PTH
⊛	103	28.00mil (0.711mm)	PTH
⊗	16	35.43mil (0.900mm)	PTH
▽	81	40.00mil (1.016mm)	PTH
⊠	2	40.16mil (1.020mm)	NPTH
⊙	4	55.12mil (1.400mm)	PTH
⊛	8	59.06mil (1.500mm)	PTH
○	22	63.00mil (1.600mm)	PTH
⊕	16	66.93mil (1.700mm)	PTH
⊗	32	74.80mil (1.900mm)	PTH
□	4	125.98mil (3.200mm)	PTH
	1692 Total		

ALL ARTWORK VIEWED FROM TOP SIDE
 BOARD #: 518520B REV: B SUN REV: Not In VersionControl
 LAYER NAME = 0005-0001-0001
 TID #: N/A
 PLOT NAME = Fabrication Drawing
 GENERATED : 1/5/2018 2:39:41 PM TEXAS INSTRUMENTS

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ENGINEER: Spectrum Digital
 LAYOUT BY: Spectrum Digital
 SCALE: 1.00
 ALTIUM DESIGNER VERSION: 17.0.11.656

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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